

Product and Process Change Notice

PCN No.	PCN03054	PCN Date	10/18/2022	Effective Date	10/18/2022
Title	Qualification of ChipMos as an additional Assembly Site for 48 ball BGA Package				

Type: Minor												
Everspin is adding ChipMos as an additional Assembly Site for 48 ball BGA Package.												
Reason For Change												
Improved manufacturing efficiency and capacity at assembly site.												
Affected Products												
<table border="1"> <thead> <tr> <th>Part Number</th><th>Description</th></tr> </thead> <tbody> <tr> <td>MR4A08BCMA35</td><td>Industrial Temp</td></tr> <tr> <td>MR4A08BMA35</td><td>Commercial Temp</td></tr> <tr> <td>MR4A08BCMA35R</td><td>Industrial Temp, T&R</td></tr> <tr> <td>MR4A08BMA35R</td><td>Commercial Temp, T&R</td></tr> </tbody> </table>			Part Number	Description	MR4A08BCMA35	Industrial Temp	MR4A08BMA35	Commercial Temp	MR4A08BCMA35R	Industrial Temp, T&R	MR4A08BMA35R	Commercial Temp, T&R
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MR4A08BCMA35	Industrial Temp											
MR4A08BMA35	Commercial Temp											
MR4A08BCMA35R	Industrial Temp, T&R											
MR4A08BMA35R	Commercial Temp, T&R											
Impact on Form, Fit, Function, Quality or Reliability												
No Impact												
Proposed First Ship Date for Change:												
November 18, 2022												
Key Material Differences												
Material	Old- UDG	New - CHM										
Die Attach (S203)	Henkel QMI-536NB (epoxy)	Henkel QMI-550 (Epoxy)										
Die Attach (B102)	QMI536NB	Nitto EM-760 (DAF)										
Die Attach (S101)	Henkel QMI-536NB (epoxy)	Henkel 2025D (Epoxy)										
Mold Compound	GE100-AT	Sumitomo G760LB										
Wire Bond	Au 4N 1.3mil	Tanaka Au 2N 0.7mil										
Substrate	HL-832NXA(Mitsubishi)	ZDT 832NXA+ AUS308										
Product Identifier												
Assembly site code = H for ChipMos Taiwan												
Supplier Qual Plan Schedule and Results												
Site package qualification is complete and all Everspin requirements met. QUA03055 QR												
Date Qualification Samples Are Available:												
Samples are generally available now but please request your specific part number to your Everspin Sales contact.												
Acceptance of Change												
Everspin will consider this change accepted unless specific conditions for acceptance are provided in writing within 30 days of receipt of this notice.												

Product and Process Change Notice

PCN No.	PCN03054	PCN Date	10/12/2022	Effective Date	10/10/2022
Title	Qualification of ChipMos as an additional Assembly Site for 48 ball BGA Package				

Contact Information		Sample Information ☒ Samples Available Now
Everspin Quality Everspin Technologies (480) 347-1084 bonnie.paro@everspin.com		Contact Everspin sales: http://www.everspin.com/contact-us-everspin-technologies If using the on-line sample request, please refer to this PCN # to receive samples.
Originator		
<u>Date</u> 10/17/2022	<u>Title</u> Senior Quality Engineer	<u>Name</u> Bonnie S. Paro 
Approval and Release		
<u>Date</u> 10/17/2022	<u>Title</u> VP of Fab Ops & Quality	<u>Name</u> Khalidoun Barakat 
<u>Date</u> 10/17/2022	<u>Title</u> VP of Backend Operations	<u>Name</u> Amit Shah 
<u>Date</u> 10/13/2022	<u>Title</u> Sr. Director of Marketing	<u>Name</u> Joe O'Hare 